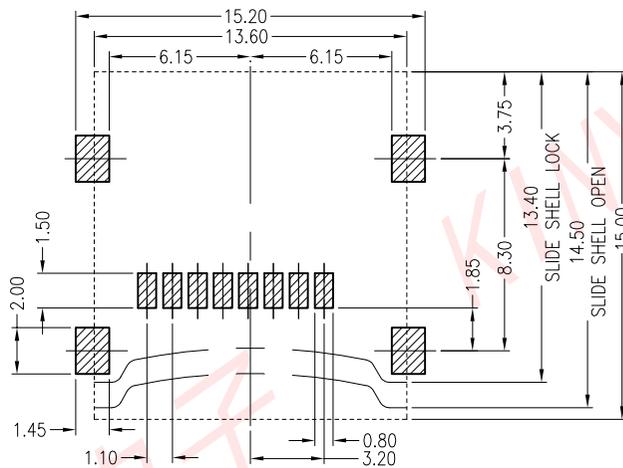
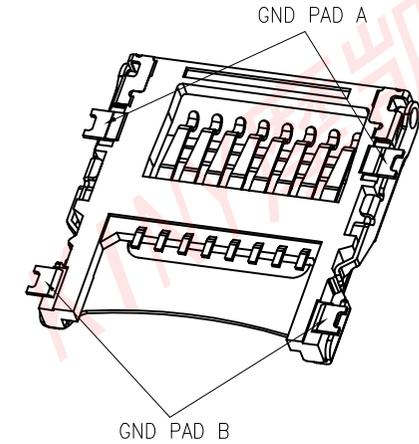
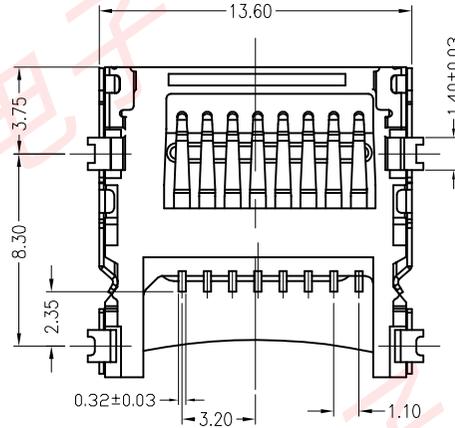
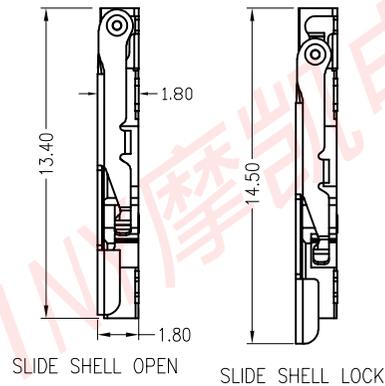
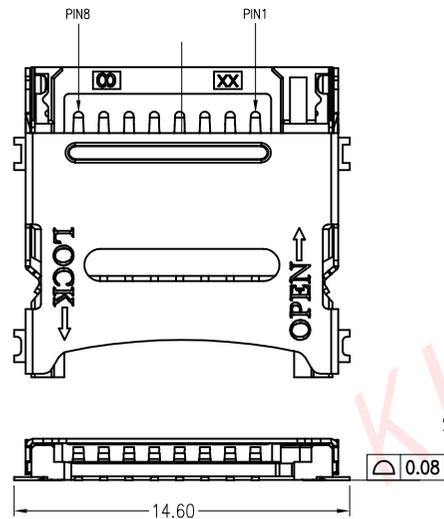


* 所有原料材质, 生产制程, 电镀必须符合HF要求



RECOMMENDED PCB LAYOUT

--- 产品外形 ▨ 焊盘

1. MATERIAL:

- 1.1 Insulator: High Temperature Thermoplastic, (LCP S475), UL Black 94V-0.
- 1.2 Contact: COPPER ALLOY (C5210, T=0.15±0.03mm)
- 1.3 Shell: SUS201-H T=0.20±0.03mm
- 1.4 GND PAD: COPPER ALLOY (C5210, T=0.15±0.03mm)

2. Plating:

- 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 100u"min Sn over Ni on solder area
- 2.2 Shell: Plated 50u"min Ni Overall
- 2.3 GND PAD A: Gold Flash Over Ni, Plated 50u"min Ni Overall
- 2.4 GND PAD B: 100u"min Sn Over Ni, Plated 50u"min Ni Overall

3. Property:

- 3.1 Current Rating :0.5A AC/DC max.
- 3.2 DIELECTRIC WITHSTANDING VOLTAGE :500V AC R.M.S. FOR 1 MINUTE.
- 3.3 Operation Temperature Range: -25°C~+70°C
- 3.4 INSULATION RESISTANCE : 100MΩ MIN. AT 500V DC
- 3.5 Contact Resistance: 60mΩ max. SWITCH RESISTANCE : 100mΩ MAX
- 3.6 OPERATING TEMPERATURE : -30°C TO +85°C
- 3.7 Durability: 5000 cycles

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE
DIMENSION TOLERANCE
X.X: ± 0.25
X.XX: ± 0.15
X.XXX: ± 0.05
ANGULAR: ± 3'

PRODUCT NAME : Micro SD 掀盖式 H=1.80mm	DRAWING: Faji	DATE: 2020.04.18
PRODUCT NO. : TF180-T1250-01-W	CHECK: Alex	DATE: 2020.04.18
DRAWING NO. : D-TF180-T1250-01-W	APPROVED: Alex	DATE: 2020.04.18
SCALE: 1:1	DWG ID: C D	REV.: A
PAGE: 1 of 1		

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REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
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